Amendments to the Claims:

Please amend the claims as shown below.

Listing of Claims:

This listing of the pending claims shall replace all previous versions of the claims.

1-43. (Canceled)

44. (Currently Amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite said front surface, wherein said semiconductor chip comprises multiple pads at said front surface;

an identity of product directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent colored encapsulation layer vertically over said identity of product, wherein said identity of product is readable through said optically transparent colored encapsulation layer as laser radiation is directed through said optically transparent colored encapsulation layer upon said identity of product, and wherein said identity of product in combination with the color of said optically transparent colored encapsulation layer represents an identification of said semiconductor chip.

45-47. (Canceled)

48. (Previously Presented) The circuit component of claim 44 further comprising an underfill between said front surface and said top surface, wherein said underfill contacts said front surface and said top surface, wherein said multiple metal bumps are in said underfill.

49. (Previously Presented) The circuit component of claim 44 further comprising multiple balls on a bottom surface of said substrate.

50-59. (Canceled)

60. (Previously Presented) The circuit component of claim 44, wherein said multiple metal bumps comprise a solder.

61. (Currently Amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite said front surface, wherein said semiconductor chip comprises multiple pads at said front surface;

an identity of manufacturer directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent colored encapsulation layer vertically over said identity of manufacturer, wherein said identity of manufacturer is readable through said optically transparent colored encapsulation layer as laser radiation is directed through said optically transparent colored encapsulation layer upon said identity of product, and wherein said identity of manufacturer in combination with the color of said optically transparent colored encapsulation layer represents an identification of said semiconductor chip.

62. (Previously Presented) The circuit component of claim 61 further comprising an underfill between said front surface and said top surface of said substrate, wherein said underfill contacts said front surface and said top surface, wherein said multiple metal bumps are in said underfill.

63. (Previously Presented) The circuit component of claim 61 further comprising multiple balls on a bottom surface of said substrate.

64. (Previously Presented) The circuit component of claim 61, wherein said multiple metal bumps comprise a solder.

65. (Currently Amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite said front surface, wherein said semiconductor chip comprises multiple pads at said front surface;

a bar code directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent colored encapsulation layer vertically over said bar code, wherein said bar code is readable through said optically transparent colored encapsulation layer as laser radiation is directed through said optically transparent colored encapsulation layer upon said ~~identity of product~~ bar code, and wherein said bar code in combination with the color of said optically transparent colored encapsulation layer represents an identification of said semiconductor chip.

66. (Previously Presented) The circuit component of claim 65 further comprising an underfill between said front surface and said top surface, wherein said underfill contacts said front surface and said top surface, wherein said multiple metal bumps are in said underfill.

67. (Previously Presented) The circuit component of claim 65 further comprising multiple balls on a bottom surface of said substrate.

68. (Previously Presented) The circuit component of claim 65, wherein said multiple metal bumps comprise a solder.